

**NXR-2000 Series
Photo-Curable
Nanoimprint Resists**

Nanoimprint Solutions

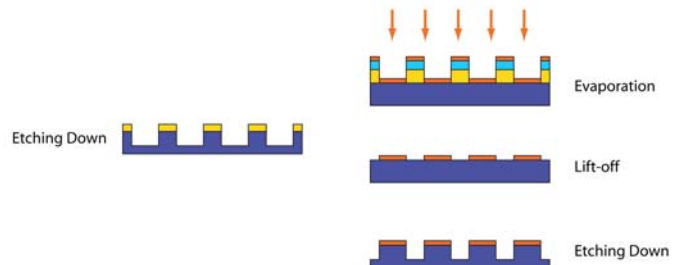
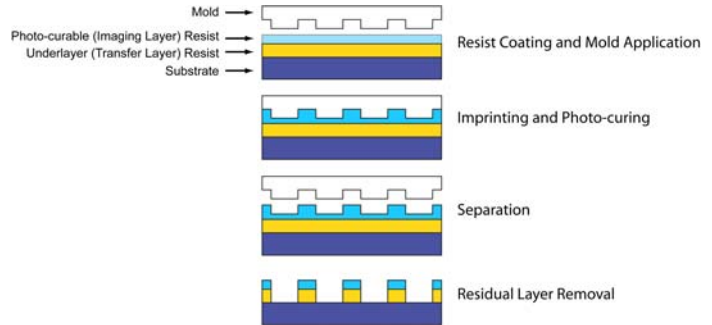
Machines Masks Resists Processes



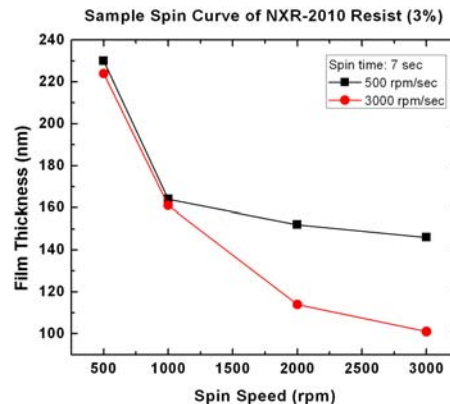
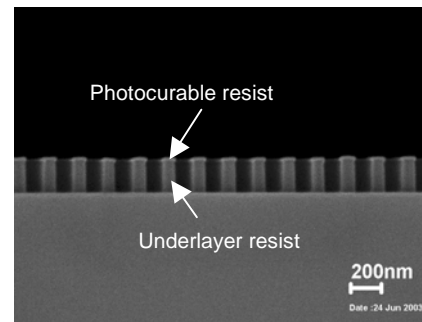
NXR-2000 series resists are general purpose photocurable nanoimprint resists designed for both sub-10 nm patterning in future nanostructure engineering and today's microfabrication. They offer excellent flow properties, high photo-sensitivity, excellent thermal stability, high etch resistance in plasma, all of which make it idea for nanoimprint applications.

Key Features

- Sub-10 nm resolution
- Room temperature operation
- Very low imprint pressure
- Strong adhesion to underlayer
- Super-low viscosity
- Excellent etch resistance
- Low UV-curing dosage



NXR-2000 Series	NXR-2010	NXR-2030
Imprint pressure	> 15 psi, Typical 30 psi	> 15 psi, Typical 30 psi
Imprint temperature	Room temperature	Room temperature
Thickness range	50 – 300 nm	50 – 300 nm
Pattern transfer	CHF3/O2 RIE	CHF3/O2 RIE
Spin coating	Yes (Spin curve available)	Yes (Spin curve available)
Sensitivity	40 mJ/cm ²	40 mJ/cm ²
Underlayer	NXR-3010 or NXR-3020	NXR-3030
Resist removal	RCA #1	RCA #1



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<http://www.nanonex.com>

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The specifications may be updated without notice.